



Dear Valued Customer

Issue date:

Taro Nishioka  
General Manager

LSIs Package Engineerings Div.  
LSIs Production Headquarters  
ROHM Co., Ltd.

**Notification of Product/Process Change**  
**Doc. No.: 102500F**

This letter intends as a formal notification of change to products which are currently supplied by ROHM Co., Ltd.

ROHM Co., Ltd. requires customers to provide acknowledgment of the receipt of this notification within 30 days from the date of this notice. Lack of acknowledgment of this notice within 30 days is considered as acceptance of the change.

After acknowledgement of the customer, lack of additional response within 90 day period constitutes acceptance of the change according to JEDEC Standard J-STD-046.

Your understanding and cooperation would be highly appreciated.

Issue Date: November 28, 2025

|                                |                                                                                                                                      |                 |                                                                                                                                                              |
|--------------------------------|--------------------------------------------------------------------------------------------------------------------------------------|-----------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Issue Date: November 25, 2025  |                                                                                                                                      |                 |                                                                                                                                                              |
| Title of change                | LSI bonding wire material change from gold to copper March 2027                                                                      |                 |                                                                                                                                                              |
| Affected product(s)            | Manufacturer part number                                                                                                             |                 | Customer part number                                                                                                                                         |
|                                | Refer to the attachment.                                                                                                             |                 |                                                                                                                                                              |
| Detailed description of change | Before                                                                                                                               |                 | After                                                                                                                                                        |
|                                | Wire Material : Gold (Au)                                                                                                            |                 | Wire Material : Copper (PdCu)<br>For some models, materials other than wire will also be changed. Please refer to the attached document for further details. |
| Reason for change              | In order to ensure stable supply of our products, we intend to submit a PCN to change the bonding wire material from gold to copper. |                 |                                                                                                                                                              |
| Anticipated impact on quality  | There are no impact on the quality.                                                                                                  |                 |                                                                                                                                                              |
| Identification of change       | Identification is possible using the internal part number on the product label.                                                      |                 |                                                                                                                                                              |
| Planned first ship date        |                                                                                                                                      | October 1, 2027 | Sample available schedule : Mar,1,2027                                                                                                                       |
| Comments                       |                                                                                                                                      |                 |                                                                                                                                                              |
| Supplier contact               | Please contact the local ROHM sales office or the authorized distributor.                                                            |                 |                                                                                                                                                              |
| Notes                          |                                                                                                                                      |                 |                                                                                                                                                              |
|                                |                                                                                                                                      |                 |                                                                                                                                                              |



Electronics for the Future

Control Number : 102500F

PCN Description

LSI bonding wire material change from gold to copper

(March 2027)

Nov. 28<sup>th</sup>, 2025

LSIs Package Engineerings Div.

LSIs Production Headquarters

ROHM Co., Ltd.

## < Report contents >

1. Background
2. Object Parts List
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**Separate detailed documents will be provided for the product-specific 4M comparison and for change point verification.**

# 1. Background

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## < Background and Purpose of change >

The price of gold has been rising in recent years, and this trend continues. In order to ensure stable supply of our products, we will submit a PCN to change the bonding wire material from gold (Au) to copper (PdCu).

Furthermore, to establish a stable supply system, we are implementing material standardization and package consolidation, which will lead to changes in package materials for certain products.

## < Schedule >

Reply due : Mar. 31, 2028

Planned first ship date : Oct 1, 2027

(We will implement the change after receiving your approval. )

## 2. Object Parts List (1)

Depending on the product, packaging materials as well as wire materials may be subject to changes.

| Part number                                                                 | Package type | Changing points                                            | Pattern |
|-----------------------------------------------------------------------------|--------------|------------------------------------------------------------|---------|
| BD83740HFP-MTR                                                              | HRP7         | Wire Material                                              | A       |
| BD3965EKV-ME2                                                               | HTQFP64V     |                                                            |         |
| BD00FC0UEFJ-ME2    BD5030MUEFJ-CE2    BD750U2EFJ-CE2                        | HTSOP-J8     |                                                            |         |
| BD8381AEFV-ME2                                                              | HTSSOP-B28   |                                                            |         |
| BD3960AFS-CE2                                                               | SSOP-A16     |                                                            |         |
| BD16805FV-ME2    BD16805PFV-ME2                                             | SSOP-B40     |                                                            |         |
| BD00FC0EFP-MGE2    BD00C0AWFP-CE2                                           | TO252-5      |                                                            |         |
| BD3360KV-ME2    BD3375KV-CE2                                                | VQFP48C      |                                                            |         |
| BM1Q001FJ-E2    BM1P061FJ-E2    BM1Q104FJ-E2                                | SOP-J8       | Wire Material                                              | B       |
| BM6104FV-CE2    BM6104RFV-CE2    BM6101FV-CE2<br>W001-CXE2    BM6108FV-LBE2 | SSOP-B20W    | Wire Material    Lead Frame    Mold Material               | C       |
| BD35395FJ-ME2▲                                                              | SOP-J8       | Wire Material    Lead Frame    Die attach    Mold Material | D       |

▲ : refer to page 10

Depending on the product, packaging materials as well as wire materials may be subject to changes.

**For the following products, the part numbers will be changed to differentiate the product lines.**

| Part number (Before) | Part number (After)      | Package type | Changing points |            |            |               | Pattern                                                                             |
|----------------------|--------------------------|--------------|-----------------|------------|------------|---------------|-------------------------------------------------------------------------------------|
| BD750L2EFJ-CE2       | BD750 <b>U</b> 2EFJ-CE2  | HTSOP-J8     | Wire Material   | Lead Frame |            | Mold Material |  |
| BD00FC0EEFJ-ME2      | BD00FC0 <b>U</b> EFJ-ME2 | HTSOP-J8     | Wire Material   | Lead Frame | Die attach | Mold Material |  |
| BD5030MEFJ-CE2       | BD5030M <b>U</b> EFJ-CE2 | HTSOP-J8     |                 |            |            |               |                                                                                     |

# 3-1. Comparison of 4M

This page provides information  
about products in patterns A to F.



Au wire products and PdCu wire products will be produced with the equivalent Machine and Method.

|              |          |                         | Before change / Au wire products        |                                           | After change / PdCu wire products     | Changing point                                                                                                                                                                                                   |
|--------------|----------|-------------------------|-----------------------------------------|-------------------------------------------|---------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Package Name |          |                         | Refer to Parts List                     |                                           | Refer to Parts List                   | No change                                                                                                                                                                                                        |
| Factory      | Assembly | Production Site         | ROHM Electronics Philippines, Inc.      | Rohm Integrated Systems Thailand Co., Ltd | Same as the left                      | No change                                                                                                                                                                                                        |
|              |          | Country                 | Philippines                             | Thailand                                  | Same as the left                      |                                                                                                                                                                                                                  |
|              |          | personnel               | Approximately 4,000 people              | Approximately 1,300 people                | Same as the left                      |                                                                                                                                                                                                                  |
|              |          | Cleanroom Design        | Below                                   |                                           | Below                                 |                                                                                                                                                                                                                  |
|              |          | DB – WB process         | Class 10,000                            |                                           | Same as the left                      |                                                                                                                                                                                                                  |
|              |          | Molding process         | Class 100,000                           |                                           | Same as the left                      |                                                                                                                                                                                                                  |
|              | Test     | Production Site         | ROHM Electronics Philippines, Inc.      | Rohm Integrated Systems Thailand Co., Ltd | Same as the left                      | No change                                                                                                                                                                                                        |
|              |          | Country                 | Philippines                             | Thailand                                  | Same as the left                      |                                                                                                                                                                                                                  |
| Man          | Assembly |                         | Qualified operators                     |                                           | Same as the left                      | No change                                                                                                                                                                                                        |
|              | Test     |                         | Qualified operators                     |                                           | Same as the left                      |                                                                                                                                                                                                                  |
| Machine      | Assembly | Die bonding process     | Fully automatic die bonding machine     |                                           | Same (Some machine is different type) | Although the equipment type will change for some packages, we will use fully automated production equipment equivalent to that of the existing production line.                                                  |
|              |          | Wire bonding process    | Fully automatic wire bonding machine    |                                           | Same (Some machine is different type) |                                                                                                                                                                                                                  |
|              |          | Molding process         | Fully automatic molding machine         |                                           | Same (Some machine is different type) |                                                                                                                                                                                                                  |
|              |          | Tie bar cutting process | Fully automatic tie bar cutting machine |                                           | Same (Some machine is different type) |                                                                                                                                                                                                                  |
|              |          | Plating process         | Fully automatic plating machine         |                                           | Same (Some machine is different type) |                                                                                                                                                                                                                  |
|              |          | Marking process         | Fully automatic laser marking machine   |                                           | Same (Some machine is different type) |                                                                                                                                                                                                                  |
|              |          | Lead forming process    | Fully automatic forming machine         |                                           | Same (Some machine is different type) |                                                                                                                                                                                                                  |
|              | Test     | Test handler            | Fully automatic handler                 |                                           | Same as the left                      | No change                                                                                                                                                                                                        |
|              |          | Tester                  | Fully automatic tester                  |                                           | Same as the left                      |                                                                                                                                                                                                                  |
|              | Taping   | Taping process          | Fully automatic taping machine          |                                           | Same as the left                      | No change                                                                                                                                                                                                        |
| Method       | Assembly | Die bonding process     | Ag paste dispensing                     |                                           | Same as the left                      | In each process step, the method remains the same, and there are no changes.<br>※ Since PdCu wire is used, production conditions have been modified and forming gas has been introduced at the processing point. |
|              |          | Wire bonding process    | Thermo-sonic bonding                    |                                           | Same as the left ※                    |                                                                                                                                                                                                                  |
|              |          | Molding process         | Transfer molding                        |                                           | Same as the left                      |                                                                                                                                                                                                                  |
|              |          | Plating process         | Electroplating                          |                                           | Same as the left                      |                                                                                                                                                                                                                  |
|              | Test     | Test process            | Socket contact                          |                                           | Same as the left                      | No change                                                                                                                                                                                                        |
| Material     | Assembly |                         | Please see next page                    |                                           | Please see next page                  | -                                                                                                                                                                                                                |

## 3-2. Comparison of 4M (Material)

This page provides information  
about products in patterns A.



The only difference between the Au wire products and the PdCu wire products is the wire material.  
We have verified this change and confirmed there are no impact on quality.

|               |                 | Before change<br>Au wire products | After change<br>PdCu wire products | Changing point                        |
|---------------|-----------------|-----------------------------------|------------------------------------|---------------------------------------|
| Lead Frame    | Frame size      | ROHM Standard design              | Same as the left                   | No change                             |
|               | Inner design    | ROHM Standard design              | Same as the left                   |                                       |
|               | Base Material   | Cu alloy                          | Same as the left                   |                                       |
|               | Surface plating | Ag plating                        | Same as the left                   |                                       |
| Die attach    |                 | Ag paste / Solder                 | Same as the left                   | No change                             |
| Wire material |                 | <b>Au</b>                         | <b>PdCu</b>                        | <b>Wire material has been changed</b> |
| Mold compound |                 | Halogen free resin                | Same as the left                   | No change                             |
| Outer plating |                 | 100%Sn                            | Same as the left                   | No change                             |
| Marking       |                 | Laser marking                     | Same as the left                   | No change                             |
| Carrier tape  |                 | ROHM standard material            | Same as the left                   | No change                             |
| Reel          |                 | ROHM standard material            | Same as the left                   | No change                             |
| Box           |                 | ROHM standard material            | Same as the left                   | No change                             |

## 3-2. Comparison of 4M (Material)

This page provides information  
about products in patterns B.



The only difference between the Au wire products and the PdCu wire products is the wire material.  
We have verified this change and confirmed there are no impact on quality.

|               |                 | Before change<br>Au wire products | After change<br>PdCu wire products | Changing point                                                                                                                |
|---------------|-----------------|-----------------------------------|------------------------------------|-------------------------------------------------------------------------------------------------------------------------------|
| Lead Frame    | Frame size      | ROHM Standard design              | Same as the left                   | No change                                                                                                                     |
|               | Inner design    | ROHM Standard design              | Same as the left                   |                                                                                                                               |
|               | Base Material   | Cu alloy                          | Same as the left                   |                                                                                                                               |
|               | Surface plating | Ag plating                        | Same as the left                   |                                                                                                                               |
| Die attach    |                 | Ag paste                          | Same as the left                   | No change                                                                                                                     |
| Wire material |                 | <b>Au</b>                         | <b>Au, PdCu</b>                    | <b>The wire material has been changed,<br/>and both Au and PdCu will be used<br/>(Chip-to-chip: Au / Chip-to-lead: PdCu).</b> |
| Mold compound |                 | Halogen free resin                | Same as the left                   | No change                                                                                                                     |
| Outer plating |                 | 100%Sn                            | Same as the left                   | No change                                                                                                                     |
| Marking       |                 | Laser marking                     | Same as the left                   | No change                                                                                                                     |
| Carrier tape  |                 | ROHM standard material            | Same as the left                   | No change                                                                                                                     |
| Reel          |                 | ROHM standard material            | Same as the left                   | No change                                                                                                                     |
| Box           |                 | ROHM standard material            | Same as the left                   | No change                                                                                                                     |

## 3-2. Comparison of 4M (Material)

This page provides information  
about products in patterns C.



For Au wire products and PdCu wire products, the wire material, lead frame and molding compound will be changed. We have verified these changes and confirmed that they have no impact on quality.

|               |                 | Before change<br>Au wire products | After change<br>PdCu wire products | Changing point                                                                                                                          |
|---------------|-----------------|-----------------------------------|------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------|
| Lead Frame    | Frame size      | ROHM Standard design              | Same as the left                   | <b>The base Material has been changed.<br/>And the frame manufacturing method has<br/>also been changed (from etching to punching).</b> |
|               | Inner design    | ROHM Standard design              | Same as the left                   |                                                                                                                                         |
|               | Base Material   | <b>Cu alloy (A)</b>               | <b>Cu alloy (B)</b>                |                                                                                                                                         |
|               | Surface plating | Ag plating                        | Same as the left                   |                                                                                                                                         |
| Die attach    |                 | Ag paste                          | Same as the left                   | No change                                                                                                                               |
| Wire material |                 | <b>Au</b>                         | <b>Au, PdCu</b>                    | <b>Wire material has been changed,<br/>and both Au and PdCu will be used<br/>(Chip-to-chip: Au / Chip-to-lead: PdCu).</b>               |
| Mold compound |                 | <b>Halogen free resin (A)</b>     | <b>Halogen free resin (B)</b>      | <b>Mold compound has been changed</b>                                                                                                   |
| Outer plating |                 | 100%Sn                            | Same as the left                   | No change                                                                                                                               |
| Marking       |                 | Laser marking                     | Same as the left                   | No change                                                                                                                               |
| Carrier tape  |                 | ROHM standard material            | Same as the left                   | No change                                                                                                                               |
| Reel          |                 | ROHM standard material            | Same as the left                   | No change                                                                                                                               |
| Box           |                 | ROHM standard material            | Same as the left                   | No change                                                                                                                               |

## 3-2. Comparison of 4M (Material)

This page provides information  
about products in patterns D and F.



For Au wire products and PdCu wire products, the wire material, lead frame, die attach material, and molding compound will be changed. We have verified these changes and confirmed that they have no impact on quality.

|               |                 | Before change<br>Au wire products | After change<br>PdCu wire products                                  | Changing point                                                                                                                                    |
|---------------|-----------------|-----------------------------------|---------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------|
| Lead Frame    | Frame size      | <b>ROHM Standard design (A)</b>   | <b>ROHM Standard design (B)</b>                                     | <b>The lead frame size has been enlarged to improve production efficiency.</b><br><br><b>※ For ▲ products, Inner design has also been changed</b> |
|               | Inner design    | <b>ROHM Standard design (A)</b>   | <b>ROHM Standard design (A)</b><br><b>※ROHM Standard design (B)</b> |                                                                                                                                                   |
|               | Base Material   | Cu alloy                          | Same as the left                                                    |                                                                                                                                                   |
|               | Surface plating | Ag plating                        | Same as the left                                                    |                                                                                                                                                   |
| Die attach    |                 | <b>Ag paste (A)</b>               | <b>Ag paste (B)</b>                                                 | <b>Ag paste has been changed</b>                                                                                                                  |
| Wire material |                 | <b>Au</b>                         | <b>PdCu</b>                                                         | <b>Wire material has been changed</b>                                                                                                             |
| Mold compound |                 | <b>Halogen free resin (A)</b>     | <b>Halogen free resin (B)</b>                                       | <b>Mold compound has been changed</b>                                                                                                             |
| Outer plating |                 | 100%Sn                            | Same as the left                                                    | No change                                                                                                                                         |
| Marking       |                 | Laser marking                     | Same as the left                                                    | No change                                                                                                                                         |
| Carrier tape  |                 | ROHM standard material            | Same as the left                                                    | No change                                                                                                                                         |
| Reel          |                 | ROHM standard material            | Same as the left                                                    | No change                                                                                                                                         |
| Box           |                 | ROHM standard material            | Same as the left                                                    | No change                                                                                                                                         |

## 3-2. Comparison of 4M (Material)

This page provides information  
about products in patterns E.



For Au wire products and PdCu wire products, the wire material, lead frame and molding compound will be changed. We have verified these changes and confirmed that they have no impact on quality.

|               |                 | Before change<br>Au wire products | After change<br>PdCu wire products | Changing point                                                             |
|---------------|-----------------|-----------------------------------|------------------------------------|----------------------------------------------------------------------------|
| Lead Frame    | Frame size      | <b>ROHM Standard design (A)</b>   | <b>ROHM Standard design (B)</b>    | <b>Lead frame size has been enlarged to improve production efficiency.</b> |
|               | Inner design    | ROHM Standard design              | Same as the left                   |                                                                            |
|               | Base Material   | Cu alloy                          | Same as the left                   |                                                                            |
|               | Surface plating | Ag plating                        | Same as the left                   |                                                                            |
| Die attach    |                 | Solder                            | Same as the left                   | No change                                                                  |
| Wire material |                 | <b>Au</b>                         | <b>PdCu</b>                        | <b>Wire material has been changed</b>                                      |
| Mold compound |                 | <b>Halogen free resin (A)</b>     | <b>Halogen free resin (B)</b>      | <b>Mold compound has been changed</b>                                      |
| Outer plating |                 | 100%Sn                            | Same as the left                   | No change                                                                  |
| Marking       |                 | Laser marking                     | Same as the left                   | No change                                                                  |
| Carrier tape  |                 | ROHM standard material            | Same as the left                   | No change                                                                  |
| Reel          |                 | ROHM standard material            | Same as the left                   | No change                                                                  |
| Box           |                 | ROHM standard material            | Same as the left                   | No change                                                                  |

## 4. Comparison of products

This page provides information  
about products in patterns A to D.



There are no changes to external dimensions or product characteristics between the Au wire products and PdCu wire products.

| Item                    | Comparison of Au wire products (Before change) and PdCu products (After change) |
|-------------------------|---------------------------------------------------------------------------------|
| Part number             | No change                                                                       |
| External dimensions     | No change                                                                       |
| Internal structures     | No change                                                                       |
| Reference land pattern  | No change                                                                       |
| Marking                 | No change                                                                       |
| Product characteristics | There are no changes to the characteristic specified listed in the datasheet.   |

## 4. Comparison of products

This page provides information  
about products in patterns E.



There are no changes to external dimensions or product characteristics between the Au wire products and PdCu wire products. However, Part number and marking have been changed.

| Item                    | Comparison of Au wire products (Before change) and PdCu products (After change)                                    |
|-------------------------|--------------------------------------------------------------------------------------------------------------------|
| Part number             | <b>Part number is changed</b>                                                                                      |
| External dimensions     | No change                                                                                                          |
| Internal structures     | No change                                                                                                          |
| Reference land pattern  | No change                                                                                                          |
| Marking                 | <b>The marking appearance will remain the same, but the characters indicating the part number will be changed.</b> |
| Product characteristics | There are no changes to the characteristic specified listed in the datasheet.                                      |

## 4. Comparison of products

This page provides information  
about products in patterns F.



There are no changes to the package dimensions between the Au wire products and the PdCu wire products.  
The characteristic values specified in the datasheet remain unchanged,  
however, change in thermal resistance have been observed.

| Item                    | Comparison of Au wire products (Before change) and PdCu products (After change)                                                                                                                                                                                                                                       |
|-------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Part number             | <b>Part number is changed</b>                                                                                                                                                                                                                                                                                         |
| External dimensions     | No change                                                                                                                                                                                                                                                                                                             |
| Internal structures     | No change                                                                                                                                                                                                                                                                                                             |
| Reference land pattern  | No change                                                                                                                                                                                                                                                                                                             |
| Marking                 | <b>The marking appearance will remain the same, but the characters indicating the part number will be changed.</b>                                                                                                                                                                                                    |
| Product characteristics | There are no changes to the characteristic values specified in the datasheet.<br><b>However, comparative measurements have confirmed that, due to a change in the Ag paste, the thermal resistance value could increase by as much as 2.5° C/W. Please confirm that this change will not affect your application.</b> |

## 5. Comparison of product label

This page provides information  
about products in patterns A to F.

A

B

C

D

E

F



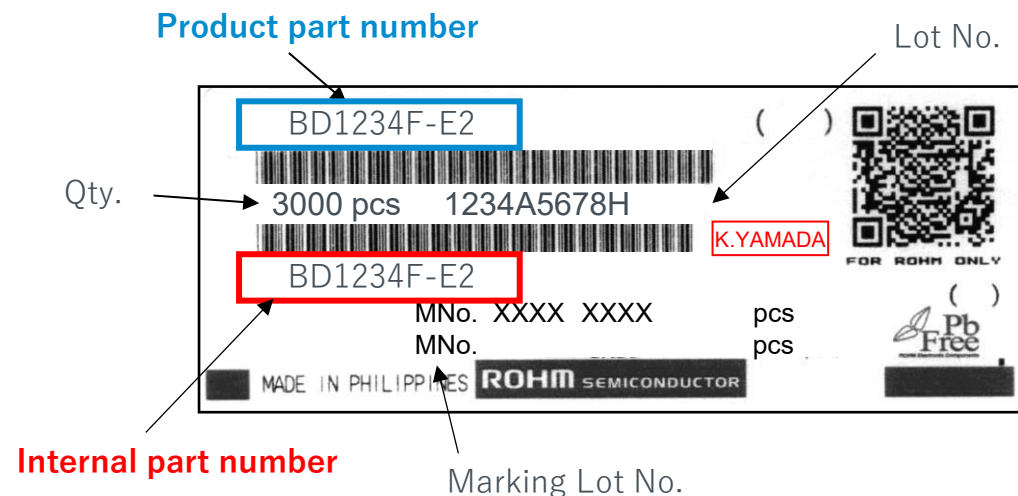
There are no changes to product part numbers before and after the change, although identification is possible using the internal part number on the product label.

<How to identify>

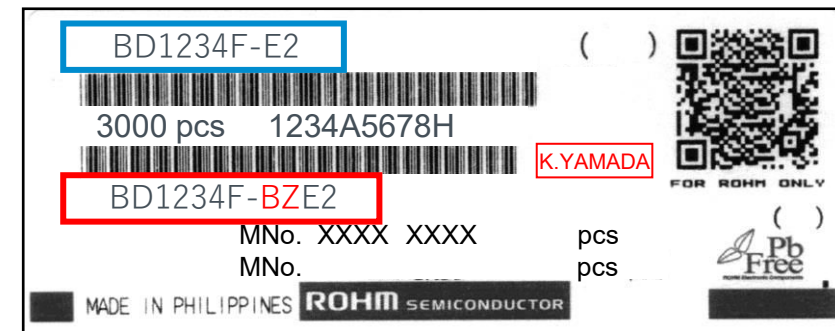
For Rohm's internal product control purposes, the internal part number differs between Au wire products (before change) and PdCu wire products (after change). The internal part number can be found on the product label on shipping packages and reeling wheels. For pattern **E** **F** products, part n**E** **F** also differs between Au wire products and PdCu wire products.

|                                   | Part number | Internal part number | Remark                              |
|-----------------------------------|-------------|----------------------|-------------------------------------|
| Before change / Au wire products  | BD1234F-E2  | BD1234F-E2           |                                     |
| After change / PdCu wire products |             | BD1234F-BZE2         | We add "BZ" on internal part number |

< Before change / Au wire products >



< After change / PdCu wire products >



## 6. Verification for changing point

This page provides information  
about products in patterns A to F.

A

B

C

D

E

F



ROHM verifies the changes in the wire material to confirm that there is no impact on quality.

| Change point                                                                                              | Concerns                                                                                                                                           | Evaluation items                              | Evaluation Results                                          | Judgement |
|-----------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|-------------------------------------------------------------|-----------|
| Melting point<br>Au:1064→Cu:1084, Pd:1555°C                                                               | There is a concern about changes in bonding performance due to changes in material properties and mechanical properties.                           | Wire bonding<br>(1st bond)                    | Results will be provided after the evaluation. (March 2027) |           |
| Tensile strength<br>100→210MPa                                                                            |                                                                                                                                                    | Wire bonding<br>(2nd bond)                    |                                                             |           |
| Elastic modulus<br>78→130GPa                                                                              |                                                                                                                                                    |                                               |                                                             |           |
| Vickers hardness<br>45→70Hv                                                                               | There is a concern about cracks under the pad due to increased impact on the pad during the first bonding, because of a harder first ball.         | Wire bonding<br>(under-pad cracks)            |                                                             |           |
| Diffusion rate with aluminum<br>$1.1 \times 10^{-4} \rightarrow 1.9 \times 10^{-16} \text{cm}^2/\text{s}$ | There is a concerns about bonding failure and a decrease in bond strength due to low bonding performance.                                          | Wire bonding<br>(Shear strength, NSOP alarms) |                                                             |           |
|                                                                                                           | There is a concern about wire breakage caused by Kirkendall voids between the wire and pad.                                                        | HTSL                                          |                                                             |           |
| Coefficient of Thermal Expansion<br>14.2→16.5ppm                                                          | There is a concern about cracks at the second bond caused by increased thermal stress.                                                             | TC                                            |                                                             |           |
| High Ionization tendency                                                                                  | There is a concern that the wire may become open caused by oxidation or corrosion.                                                                 | AC                                            |                                                             |           |
|                                                                                                           |                                                                                                                                                    | THB                                           |                                                             |           |
| Using forming gas                                                                                         | There is a concern that there may be a decrease in wire bonding quality due to temperature drops caused by forming gas or abnormal gas flow rates. | Wire bonding<br>(1st bond)                    |                                                             |           |
|                                                                                                           |                                                                                                                                                    | Wire bonding<br>(2nd bond)                    |                                                             |           |

## 7. Reliability tests

This page provides information  
about products in patterns A to F.

A

B

C

D

E

F



Standard reliability tests will be performed.

【Pre conditions】

|                  |                                        |                |               |
|------------------|----------------------------------------|----------------|---------------|
| MSL              | JEDEC LEVEL 1                          | JEDEC LEVEL 2a | JEDEC LEVEL 3 |
| Drying           | 125°C 24h                              |                |               |
| Moisture soaking | 85°C 85% 168h                          | 60°C 60% 120h  | 30°C 70% 192h |
| Reflow profiles  | Pb free reflow profiles (260°C) 3times |                |               |

### ■ Reliability test results

| Items                                   | Standards   | Conditions      | Duration | Sample Qty.    | Fail                                                              | Judgement |
|-----------------------------------------|-------------|-----------------|----------|----------------|-------------------------------------------------------------------|-----------|
| Resistance to soldering heat<br>PC      | J-STD-020   | MSL 2a          | -        | 77 pcs x 3 Lot | Results will be provided<br>after the evaluation.<br>(March 2027) |           |
| Temperature Humidity Bias<br>THB        | JESD22-A101 | 85°C 85% w/bias | 2000h    | 77 pcs x 3 Lot |                                                                   |           |
| Autoclave<br>AC                         | JESD22-A102 | 121°C 100% 2atm | 192h     | 77 pcs x 3 Lot |                                                                   |           |
| Temperature Cycling<br>TC               | JESD22-A104 | -65°C⇔150°C     | 1000cyc  | 77 pcs x 3 Lot |                                                                   |           |
| High Temperature Storage Life<br>HTSL   | JESD22-A103 | 150°C           | 2000h    | 77 pcs x 3 Lot |                                                                   |           |
| High Temperature Operating Life<br>HTOL | JESD22-A108 | 125°C w/bias    | 1000h    | 77 pcs x 3 Lot |                                                                   |           |



Electronics for the Future

Public (External) PN

BD00C0AWFP-CE2

BD00FC0EFP-MGE2

BD00FC0UEFJ-ME2

BD16805FV-ME2

BD16805PFV-ME2

BD3360KV-ME2

BD3375KV-CE2

BD35395FJ-ME2

BD3960AFS-CE2

BD3965EKV-ME2

BD5030MUEFJ-CE2

BD750U2EFJ-CE2

BD83740HFP-MTR

BD8381AEFV-ME2

BM1P061FJ-E2

BM1Q001FJ-E2

BM1Q104FJ-E2

BM6101FV-CE2

BM6104FV-CE2

BM6104RFV-CE2

BM6108FV-LBE2

W001-CXE2